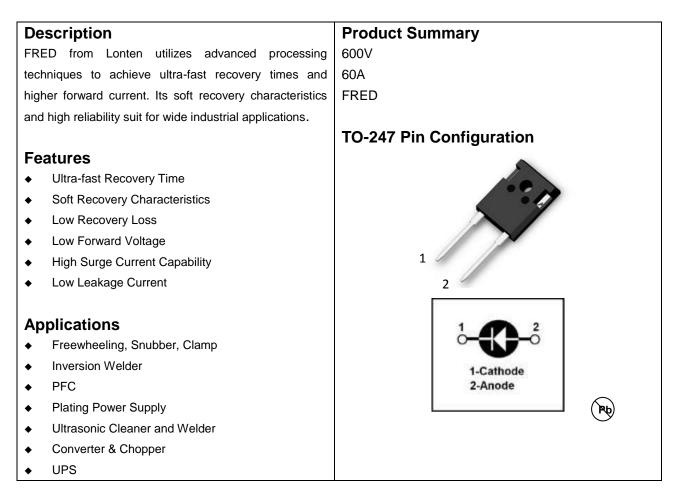


600V 60A Ultra-Fast Recovery Diode



Absolute Maximum Ratings T_c = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Maximum D.C. Reverse Voltage	V _R	600	V
Maximum Repetitive Reverse Voltage	V _{RRM}	600	V
Average Forward Current(Tc = 110° C)	I _{F(AV)}	60	А
RMS Forward Current(Tc = $110^{\circ}C$)	I _{F(RMS)}	90	А
Non-Repetitive Surge Forward Current(TJ =	I _{FSM}	600	А
45℃,t=10ms,50Hz,Sine)			
Power Dissipation	P _D	250	W
Junction Temperature Range	TJ	-40 to +150	°C
Storage Temperature Range	T _{STG}	-40 to +150	°C
Module-to-Sink(Recommended M3)	Torque	1.1	Nm
	Weight	6.0	g

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R _{θJC}	0.5	°C/W



Package Marking and Ordering Information

Device	Device Package	Marking	
LDB60U60W4	TO-247	LDB60U60W4	

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{RM} Reverse Leakage Current	Devenue la characteria	V _R =600V			10	uA
	Reverse Leakage Current	V _R =600V, T _J =125℃			1000	uA
V _F Forward \		I _F =60A		1.9	2.4	V
	Forward voltage	I _F =60A, T _J =125℃		1.7		V
t _{rr} Reverse Recovery Time		I _F =1A, V _R =30V,		25		ns
		di _F /dt=-200A/us				
t _{rr}	Reverse Recovery Time	V _R =300V, I _F =60A		45		ns
I _{RRM}	Max. Reverse Recovery Current	di _F /dt=-200A/us, T _J =25℃		2.5		Α
t _{rr}	Reverse Recovery Time	V _R =300V, I _F =60A		125		ns
I _{RRM}	Max. Reverse Recovery Current	di _F /dt=-200A/us, T _J =125℃		6.5		Α

Electrical Characteristics T_J = 25°C unless otherwise noted

Electrical Characteristics Diagrams

Figure 1. Forward Voltage Drop vs Forward Current

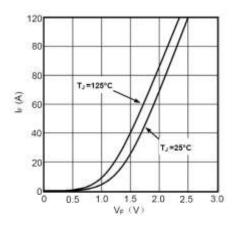
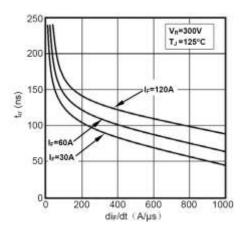


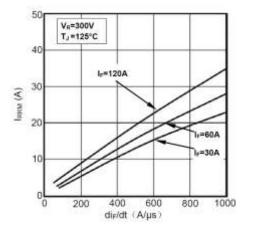
Figure 2. Reverse Recovery Time vs diF/dt

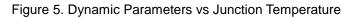




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Figure 3. Reverse Recovery Current vs diF/dt





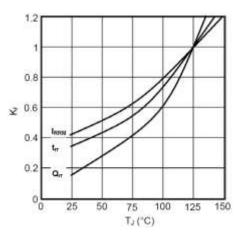


Figure 4. Reverse Recovery Charge vs diF/dt

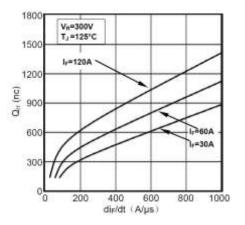


Figure 6. Transient Thermal Impedance

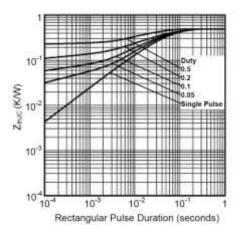
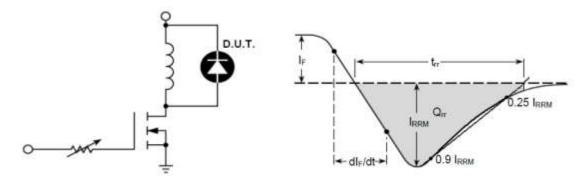


Figure 7. Diode Reverse Recovery Test Circuit and Waveform

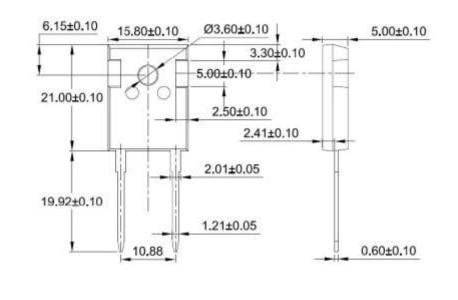


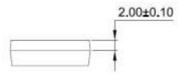


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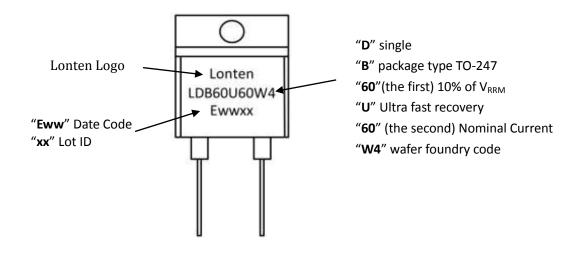
Figure 8. Package Outline

Dimensions in Millimeters





Marking Information





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